

Amendments to the Claims

Claim ① (currently amended): A semiconductor module,
comprising:

a substrate body having an insulating ceramic layer with a top side, and a metal layer fixedly joined to said top side of said insulating ceramic layer, said substrate body being one of a direct copper bonded (DCB) substrate and an active metallic brazed (AMB) substrate;

B at least one connection conductor ~~joined~~ laser-welded to said metal layer ~~by welding~~; and

at least one semiconductor component disposed directly on said substrate body facing said metal layer.

Claim ② (original): The semiconductor module according to claim 1, wherein said insulating ceramic layer of said substrate body is formed of Al_2O_3 .

Claim ③ (original): The semiconductor module according to claim 1, wherein said metal layer is formed of at least one material selected from the group consisting of copper and aluminium.

Claim 4 (cancelled).

Claim (5) (original): The semiconductor module according to claim 1, wherein said insulating ceramic layer contains AlN.

Claim 6 (original): The semiconductor module according to claim 1, wherein said insulating ceramic layer contains BeO.

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Claim (7) (original): The semiconductor module according to claim 1, wherein said connection conductor is one of a plurality of connection conductors each formed of a at least one material selected from the group consisting of Cu, Al, CuSn and CnZn.

Claim (8) (original): The semiconductor module according to claim 1, including a coating disposed on said metal layer.

Claim 9 (original): The semiconductor module according to claim 1, wherein said connection conductor has a foot which is bent at right angles.

Claim 10 (original): The semiconductor module according to claim 9, wherein said foot has at least one slot formed therein.

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Claim 11 (original): The semiconductor module according to claim 10, wherein said slot has a given width that is approximately equal to a thickness of said foot.

Claims 12-13 (withdrawn).
